

Supported Materials

Undercooling, thermal stability and application in exothermic catalytic reaction of SiO₂ encapsulated SnZnCu microspheres

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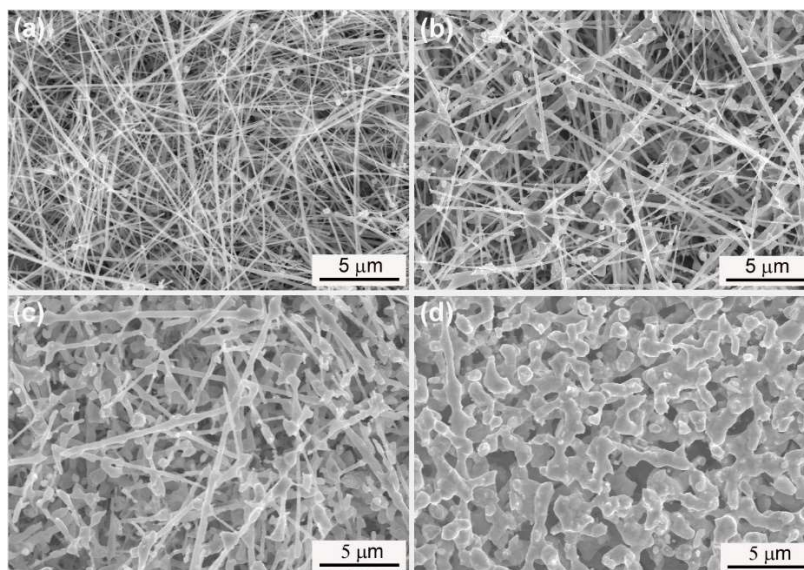


Figure S1 SEM images of Cu nanowires before and after calcinated for 30 min in Ar atmosphere at different temperatures:(a) as-prepared, (b) calcinated at 500 °C, (c) calcinated at 600°C and (d) calcinated at 700°C.

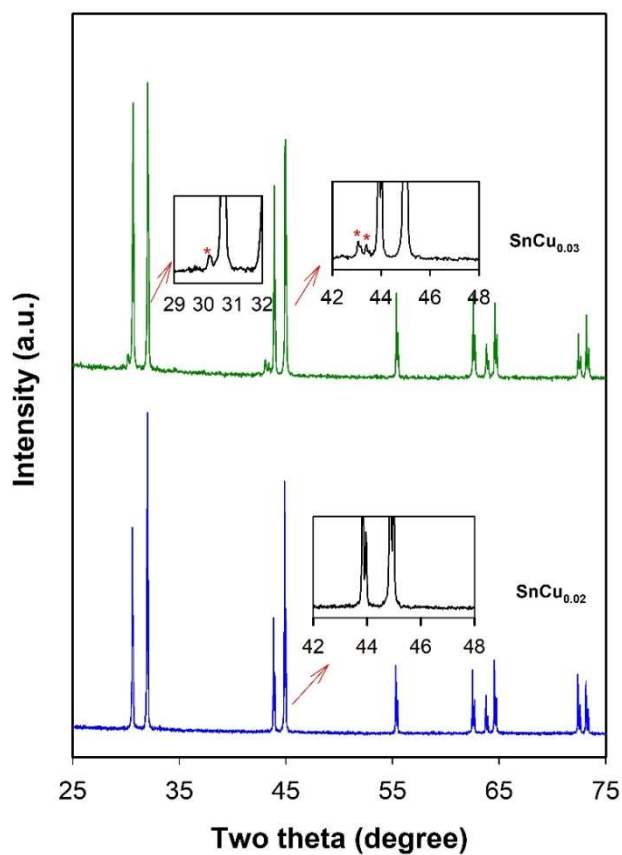


Figure S2 XRD patterns of SnCu_{0.02} and SnCu_{0.03} microspheres.

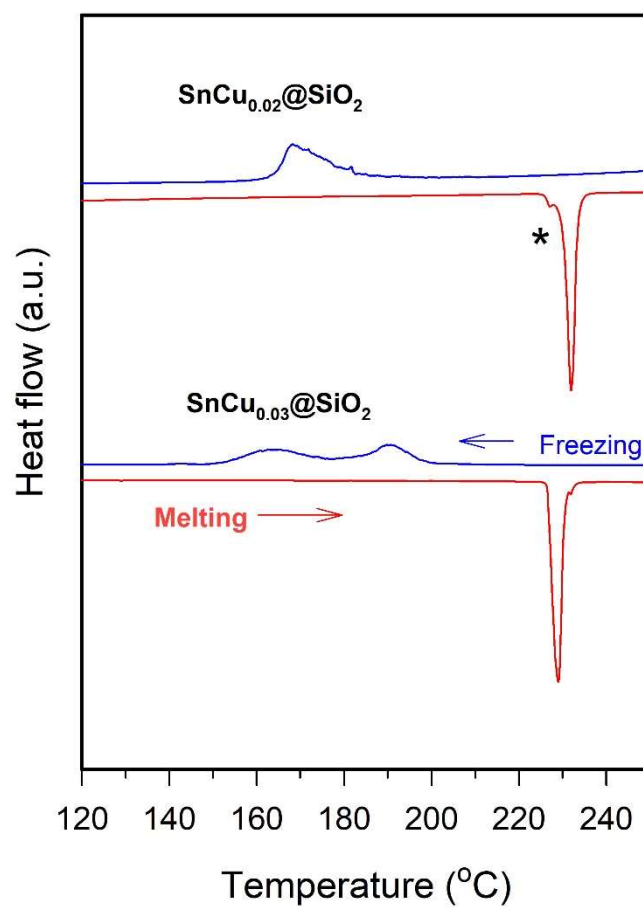


Figure S3 DSC curves of $\text{SnCu}_{0.02}@\text{SiO}_2$ and $\text{SnCu}_{0.03}@\text{SiO}_2$ microspheres